

July 18, 2003

To: Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Fr: George O. Saile Reg. No. 19,572  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

**Continuation of**  
Serial No.: 09/557,395 4/24/00  
**SHAU-LIN SHUE, MING-HSING TSAI**  
**METHOD FOR INTEGRATING LOW-K MATERIALS IN**  
**SEMICONDUCTOR FABRICATION**

#### **PRELIMINARY AMENDMENT**

Dear Sir:

This is a preliminary amendment for the above referenced Continuation Application. Please amend the above identified application for patent as follows:

#### **CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on July 21, 2003.

Stephen B. Ackerman, Reg. No. 37,761

Signature/Date

 7/21/03

June 27, 2003

To: Commissioner of Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

From: George O. Saile, Reg. No. 19,572  
28 Davis Avenue  
Poughkeepsie, N. Y. 12603

Subject:

**Continuation of**

Serial No.: 09/557,395 Filing Date: 04/24/00

Inventor: Shue et al.

Title: Method for Integrating Low-K Materials in Semiconductor Fabrication

Art Unit: 2812 Examiner: Pham, Thanhha

Attorney Docket: TSMC99-132CC

**PRELIMINARY AMENDMENT**

Dear Sirs:

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